

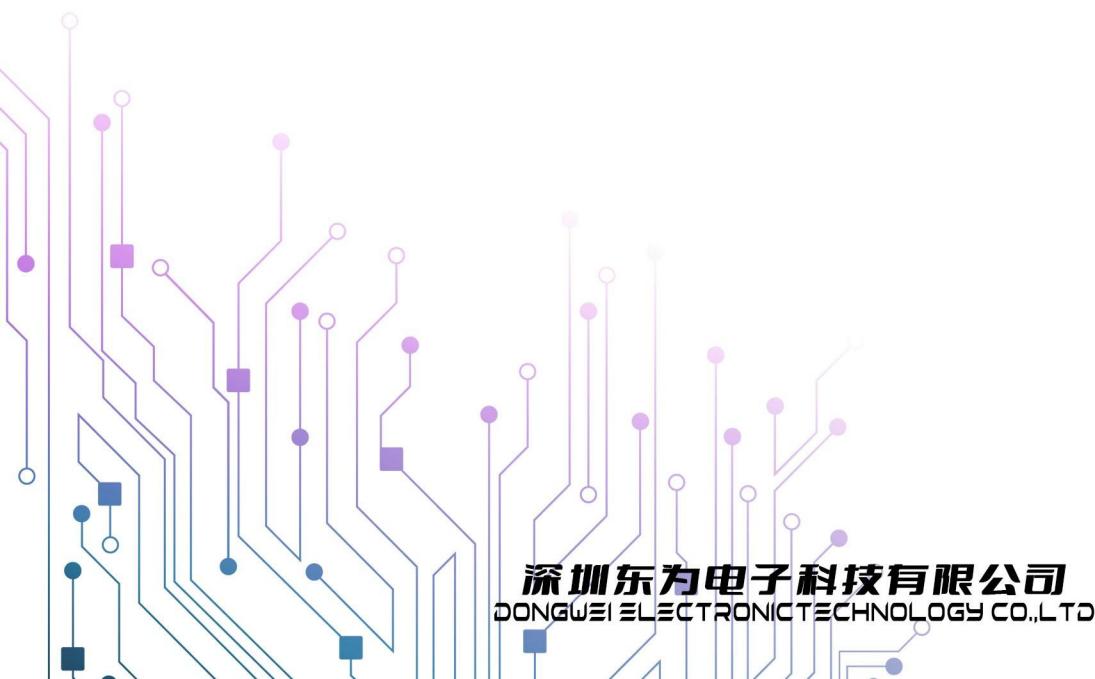


# 产品规格手册

PRODUCT SPECIFICATION MANUAL

## XWN1018K

N-Ch Fast Switching MOSFETs  
TO-252/100V/50A/17mΩ





- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary

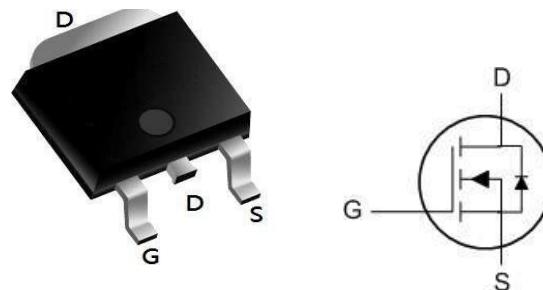
BVDSS	RDS(on)	ID
100V	17 mΩ	50A

### Description

The XWN1018K is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDS(on) and gate charge for most of the synchronous buck converter applications.

The XWN1018K meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### TO252 Pin Configuration



### Package Marking and Ordering Information

Product	Package	Marking	Packing	Min Unit Quantity
XWN1018K	TO-252	N1018K	2500PCS/Reel	5000PCS

### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		100	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_c = 25^\circ\text{C}$	50	A
		$T_c = 100^\circ\text{C}$	30	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		150	A
EAS	Single Pulsed Avalanche Energy <sup>note2</sup>		62.6	mJ
$P_D$	Power Dissipation	$T_c = 25^\circ\text{C}$	73	W
$R_{eJC}$	Thermal Resistance, Junction to Case		2.0	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +175	$^\circ\text{C}$

## Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

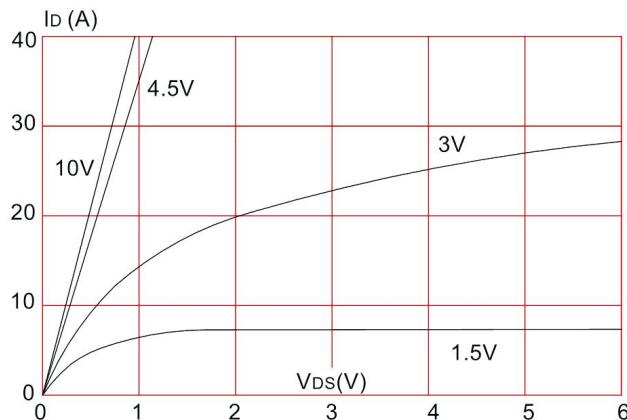
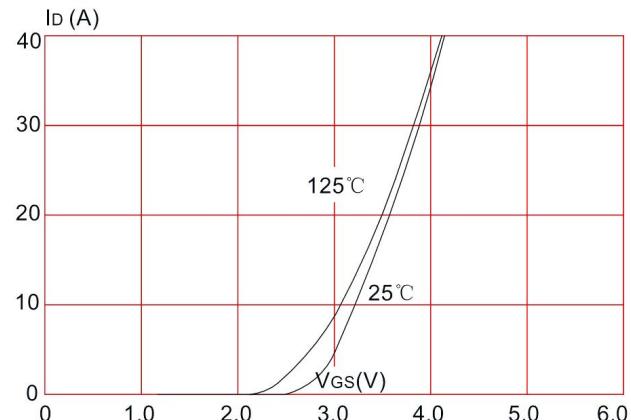
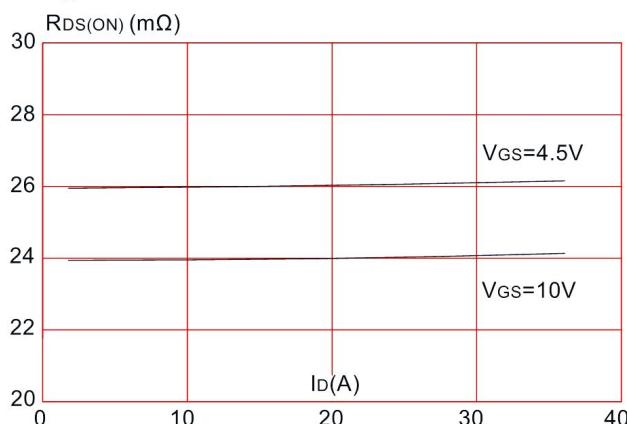
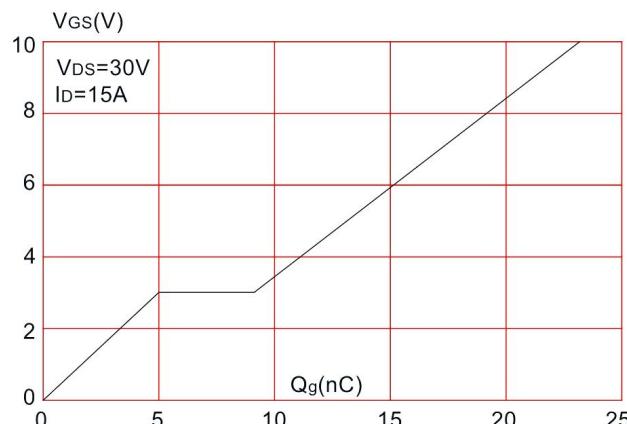
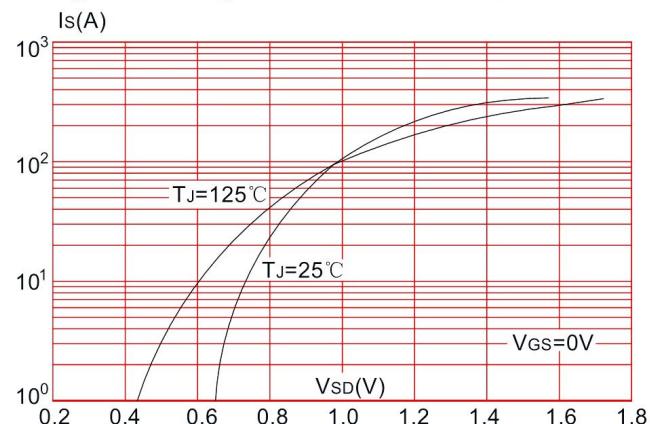
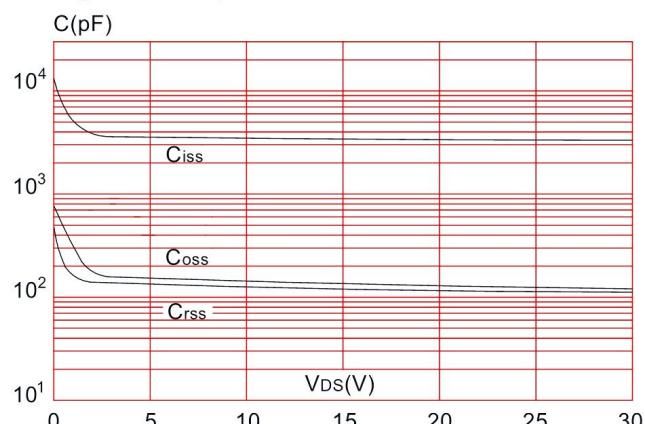
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=100\text{V}$ , $V_{\text{GS}}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{\text{DS}(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	-	17	28	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	-	22	32	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	-	3727	-	pF
$C_{\text{oss}}$				180	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	148	-	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=30\text{V}$ , $I_D=15\text{A}$ , $V_{\text{GS}}=10\text{V}$	-	40	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	6.2	-	nC
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge		-	28	-	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=30\text{V}$ , $I_D=15\text{A}$ , $R_G=1.8\Omega$ , $V_{\text{GS}}=10\text{V}$	-	22	-	ns
$t_r$	Turn-on Rise Time		-	182	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	80	-	ns
$t_f$	Turn-off Fall Time		-	142	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	50	A
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	150	A
$V_{\text{SD}}$	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_S=30\text{A}$	-	-	1.2	V
$\text{trr}$	Body Diode Reverse Recovery Time	$\text{IF}=30\text{A}, \text{dI}/\text{dt}=100\text{A}/\mu\text{s}$	-	71	-	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge		-	145	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

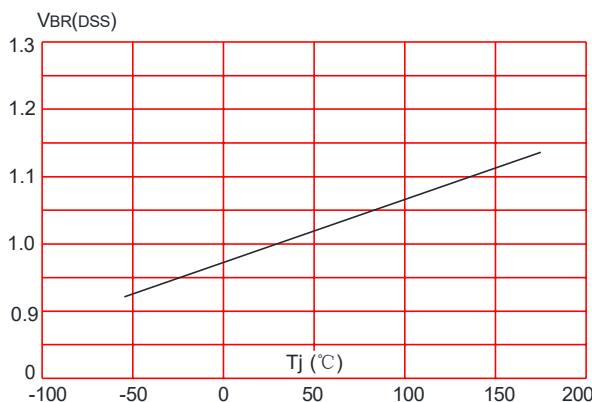
2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=50\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{\text{AS}}=14.5\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

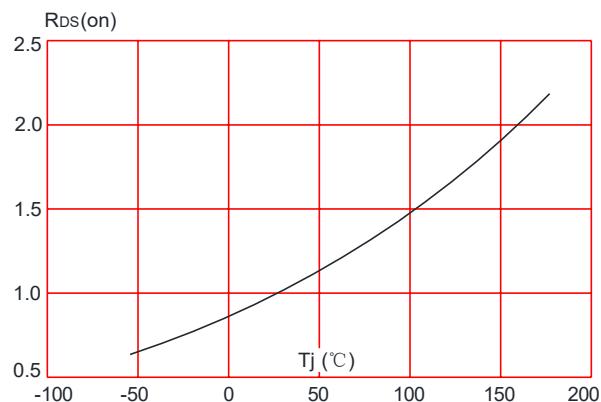
## Typical Performance Characteristics

**Figure1:** Output Characteristics**Figure 2:** Typical Transfer Characteristics**Figure 3:** On-resistance vs. Drain Current**Figure 5:** Gate Charge Characteristics**Figure 4:** Body Diode Characteristics**Figure 6:** Capacitance Characteristics

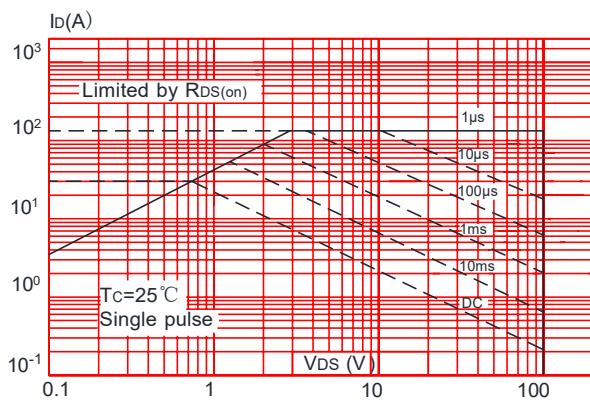
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



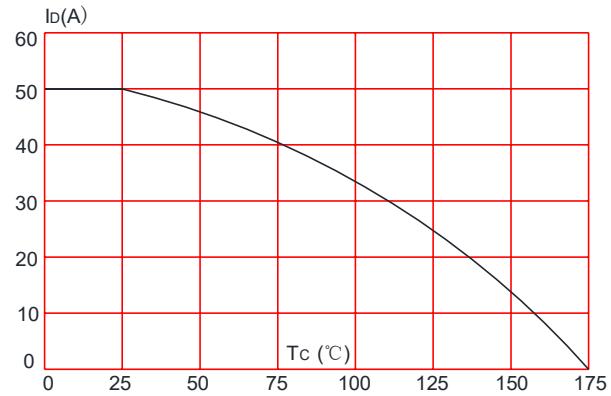
**Figure 8:** Normalized on Resistance vs. Junction Temperature



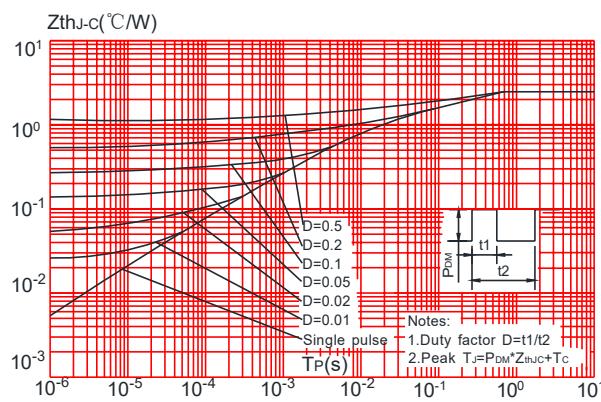
**Figure 9:** Maximum Safe Operating Area



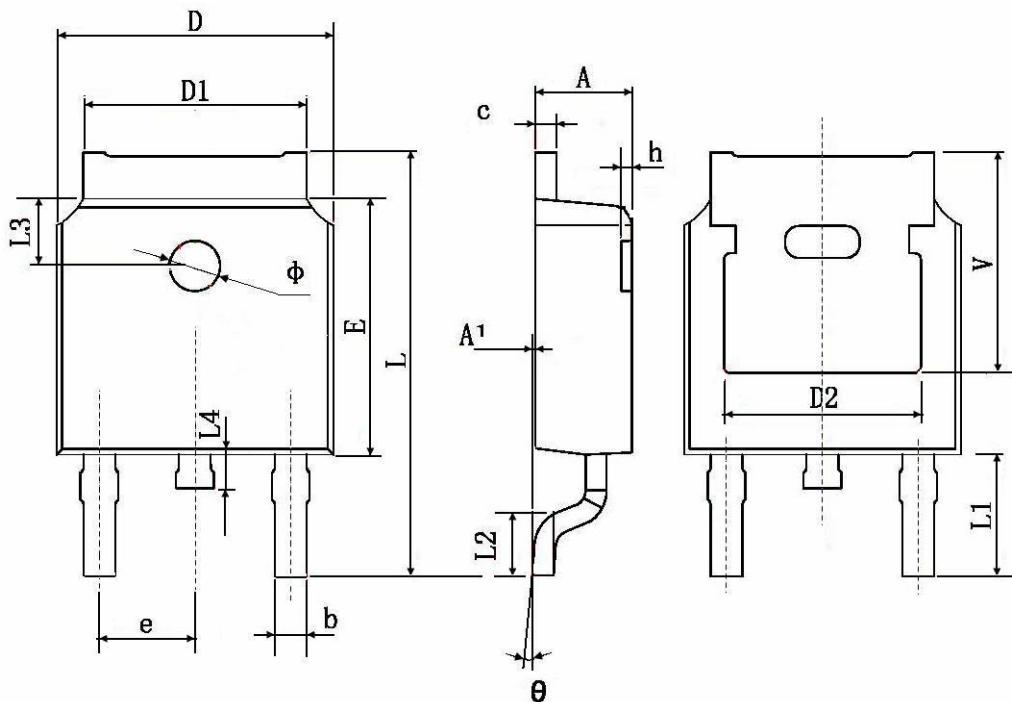
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



## TO-252 Package outline



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	